

XTL2069L

32.000000 MHz
Crystal Unit



SM1210-4

Features:

- Surface Mount Hermetic Package
- Excellent Reliability Performance
- Good Frequency Perturbation and Stability over temperature
- Ultra Miniature Package
- Moisture Sensitive Level (MSL): Level 1

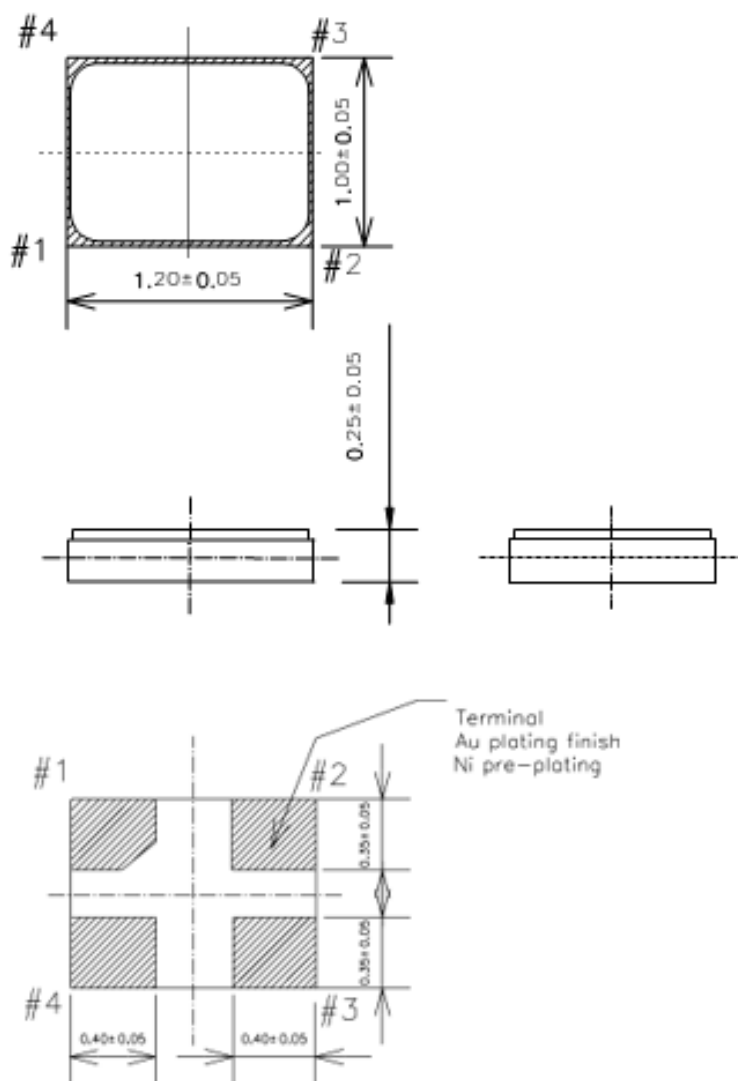
Description and Applications:

Surface mount 1.2mmx1.0mm crystal unit for use in wireless communications devices, especially for a need of ultra miniature package for mobility.

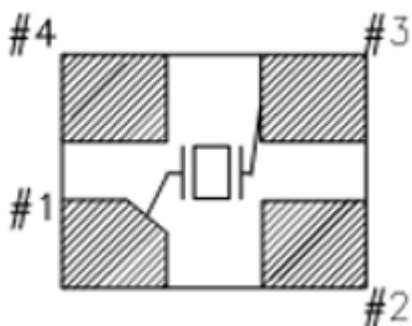
Electrical Specifications:

XTL2069L	Specification
Nominal Frequency	32.000000 MHz
Mode of Oscillation	Fundamental
Storage Temperature Range	-40°C to +85°C
Operating Temperature Range	-20°C to +70°C
Frequency Stability over Operating Temperature Range	+/-20 ppm (referred to the value at 25°C)
Frequency Make Tolerance (FL)	+/-10 ppm @ 25°C +/- 3°C
Equivalent Series Resistance (ESR)	100 Ω max
Nominal Drive Level	50uW typical and 200uW max
Shunt Capacitance (Co)	3.0 pF max
Load Capacitance (CL)	6 pF
Aging	+/-2 ppm/ year
Insulation Resistance	500 M Ω min./DC 100V
Marking	Laser Marking

Mechanical Dimensions (mm):



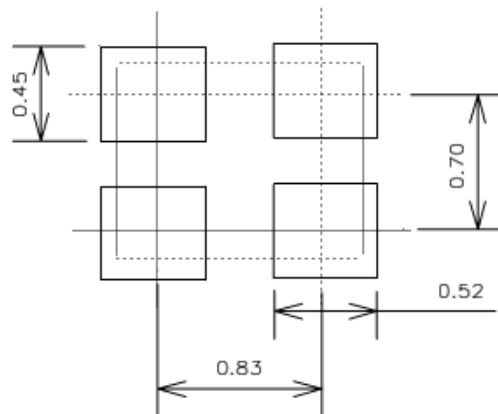
Terminal land connection (Top View)



#1	XTAL IN
#2	GND (CONNECTIO WITH COVER)
#3	XTAL OUT
#4	NC

Recommended Land Pattern: (unit: mm)

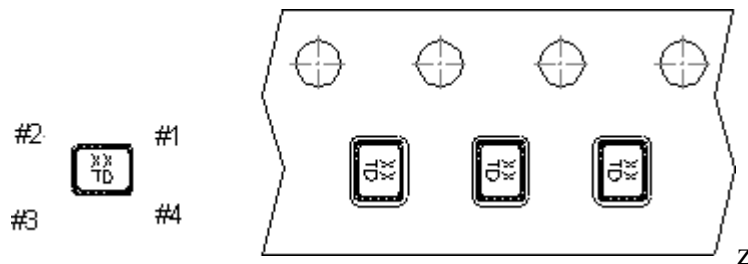
LAND PATTERN (TYPICAL)



Marking:

Line 1: XX; Frequency (32)

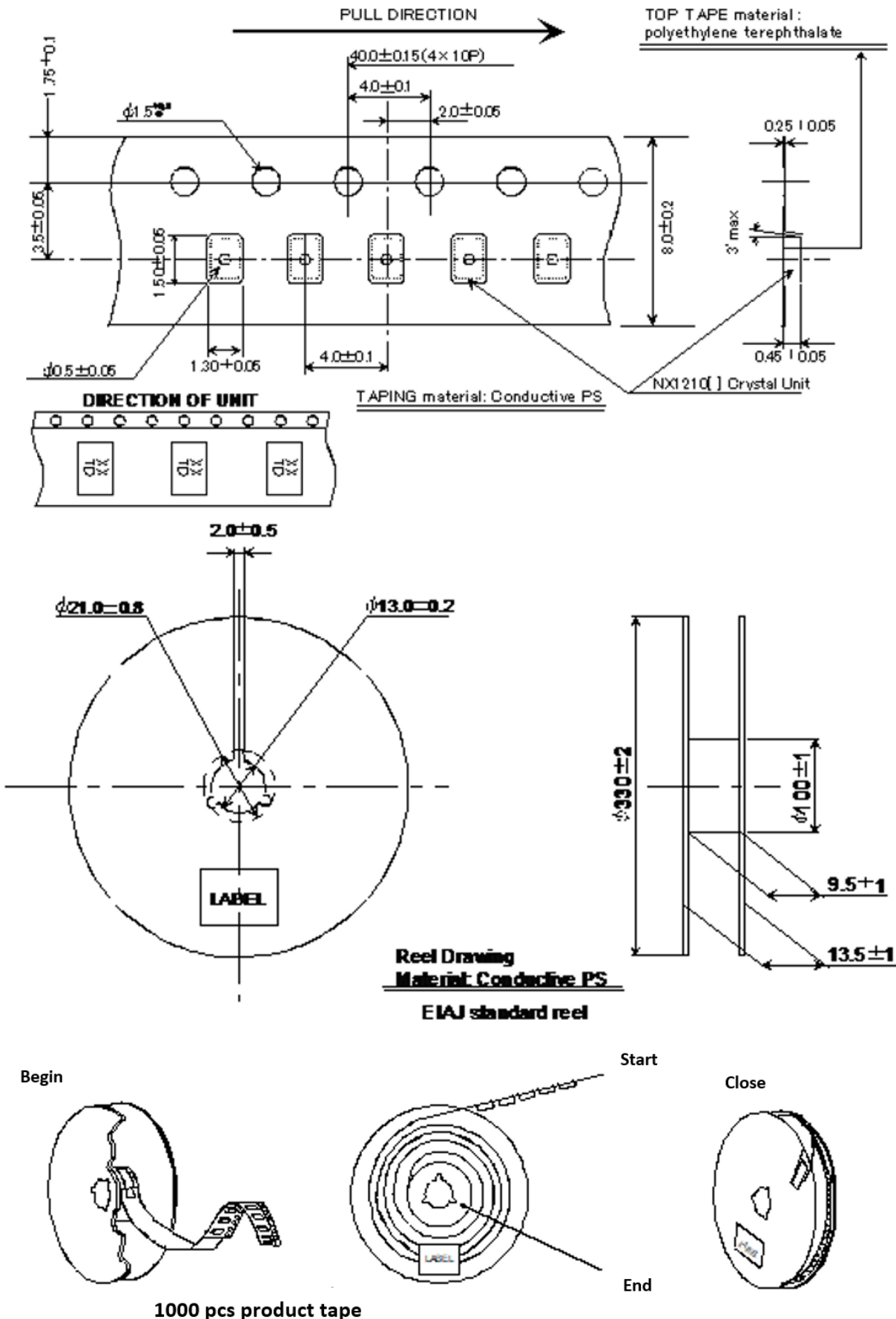
Line 2: T; Traceable Code + D; date Code of Year/Month



Date Code Table: Year/Month

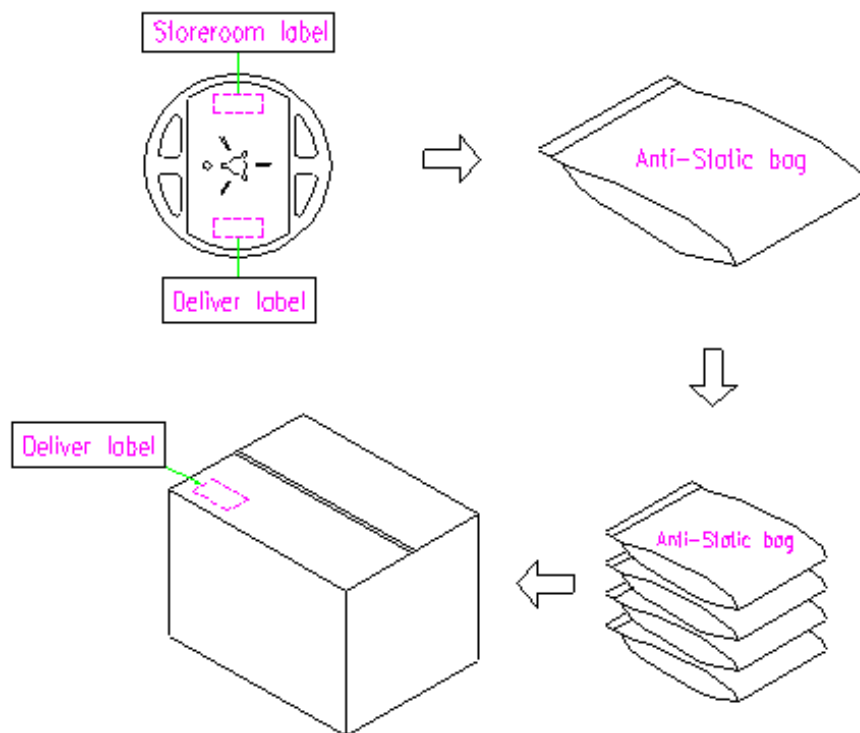
Year/Month	1	2	3	4	5	6	7	8	9	10	11	12
2012	a	b	c	d	e	f	g	h	i	j	k	m
2013	n	p	q	r	s	t	u	v	w	x	y	z
2014	A	B	C	D	E	F	G	H	J	K	L	M
2015	N	P	Q	R	S	T	U	V	W	X	Y	Z
2016	a	b	c	d	e	f	g	h	i	j	k	m
2017	n	p	q	r	s	t	u	v	w	x	y	z
2018	A	B	C	D	E	F	G	H	J	K	L	M
2019	N	P	Q	R	S	T	U	V	W	X	Y	Z
2020	a	b	c	d	e	f	g	h	i	j	k	m
2021	n	p	q	r	s	t	u	v	w	x	y	z
2022	A	B	C	D	E	F	G	H	J	K	L	M
2023	N	P	Q	R	S	T	U	V	W	X	Y	Z
2024	a	b	c	d	e	f	g	h	i	j	k	m
2025	n	p	q	r	s	t	u	v	w	x	y	z

Tape/Reel Dimensions (mm):

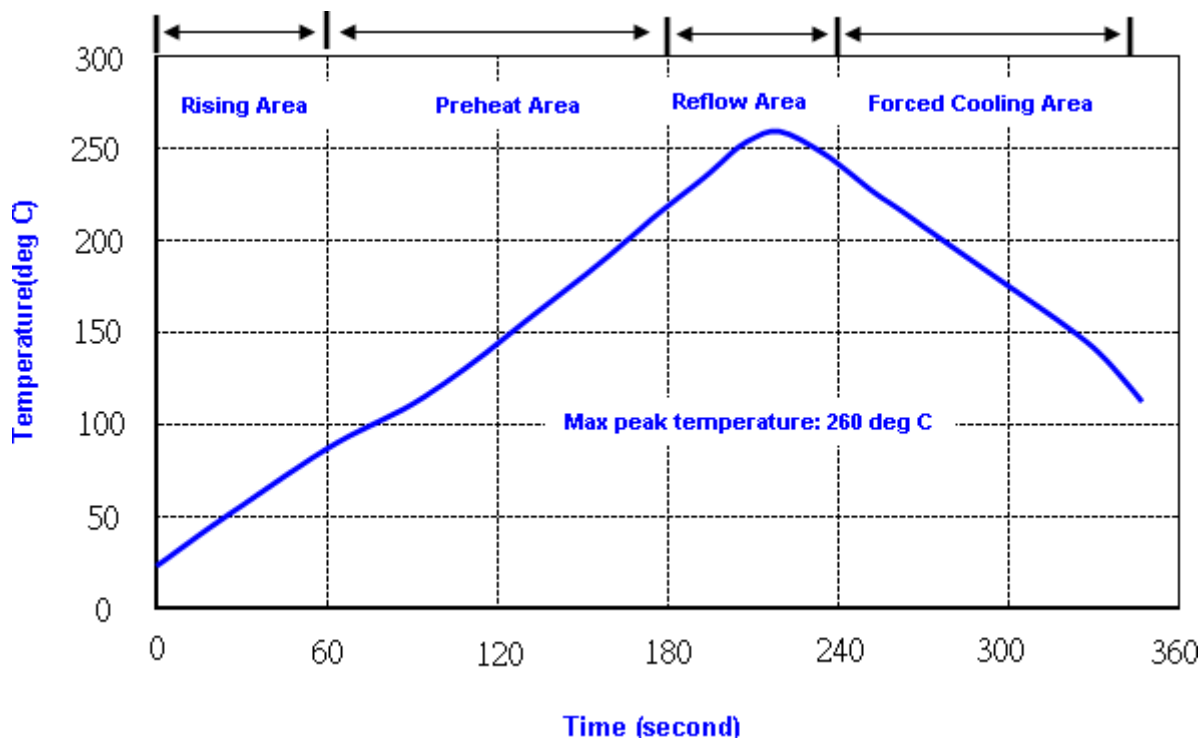


Packing Quantity/Packing:

3K pcs maximum per reel



Reflow Profile:



Note: 1. Max peak temperature: 260 $\pm$ 5 deg C; Time: 10 $\pm$ 2 sec
2. Temperature: 217 $\pm$ 5 deg C; Time: 90~100 sec

Reliability Specifications

Test name	Test process / method	Reference standard
Mechanical characteristics		
resistance to Soldering heat (IR reflow)	Temp./ Duration : 265°C /10sec ×2 times Total time : 4min.(IR-reflow)	EIAJED-4701 -300(301)M(II)
Vibration	Total peak amplitude : 1.5mm Vibration frequency : 10 to 2000 Hz Sweep period : 20 minute Vibration directions : 3 mutually perpendicular Duration : 2 hr / direc.	MIL-STD 202G method 204
Mechanical Shock	directions : 3 impacts per axis Acceleration : 3000g's, +20/-0 % Duration : 0.3 ms (total 18 shocks) Waveform : Half-sine	MIL-STD 202G method 213
Solderability	Solder Temperature:265±5°C Duration time: 5±0.5 seconds.	J-STD-002
Environmental characteristics		
Thermal Shock	Heat cycle conditions -40 °C (30min) ↔ 85 °C (30min) * cycle time : 10 times	MIL-STD 883G method 1010.8
Humidity test	Temperature : 85 ± 2 °C Relative humidity : 85% Duration : 96 hours	MIL-STD 202G method 103
Dry heat (Aging test)	Temperature : 125 ± 2 °C Duration : 168 hours	MIL-STD 202G method 108A
Cold resistance (Low Temp Storage)	Temperature : -40 ± 2 °C Duration : 96 hours	IEC 60068-2-1



CAUTION: Electrostatic Sensitive Device. Observe precautions for handling.

NOTES:

1. The design, manufacturing process, and specifications of this device are subject to change.
2. US or International patents may apply.
3. RoHS compliant from the first date of manufacture.